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Title: JP2001015912A2: MULTILAYERED PRINTED WIRING BOARD AND PRODUCTION THEREOF

Country: JP Japan

Kind: A2 Document Laid open to Public inspection

Inventor: SEKINE KOJI;

Assignee: IBIDEN CO LTD

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Published / Filed: 2001-01-19 / 1999-07-02

Application Number: JP1999000189208

IPC Code: H05K 3/46; H05K 3/00; H05K 3/28;

Priority Number: 1999-07-02 JP1999000189208

Abstract: PROBLEM TO BE SOLVED: To provide a multilayered printed wiring board and a method for producing the multilayered printed wiring board by which the arrangement density of through hole can be improved and the thickness thereof be made smaller.

SOLUTION: Interlayer resin insulation layers 24 and 38 and a core substrate 50 for upper layer are built up on a core substrate 10 for lower layer. Therefore, a plurality of core substrates 10 and 50 ensure the strength of a multilayered printed wiring board, so that the core substrate can be formed thin, and the thickness of the multilayered printed wiring board be also made small. In addition, a fine non-through hole 10a can be easily made by a laser, and a through hole 14 with a small diameter can be formed.

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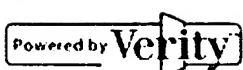
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